

STP12NK60Z STF12NK60Z, STW12NK60Z

N-channel 650 V @ Tjmax, 0.53 Ω, 10 A TO-220, TO-220FP, TO-247 Zener-protected SuperMESH™ Power MOSFET

Features

Туре	V _{DSS} (@Tjmax)	R _{DS(on)} max	I _D	P _W
STP12NK60Z	650 V	<0.640 Ω	10 A	150 W
STF12NK60Z	650 V	<0.640 Ω	10 A	35 W
STW12NK60Z	650 V	<0.640 Ω	10 A	150 W

- Extremely high dv/dt capability
- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitances
- Very good manufacturing repeatability



Switching applications

Description

The SuperMESH™ series is obtained through an extreme optimization of ST's well established strip-based PowerMESH™ layout. In addition to pushing on-resistance significantly down, specialties is taken to ensure a very good dv/dt capability for the most demanding application. Such series complements ST full range of high voltage Power MOSFETs.

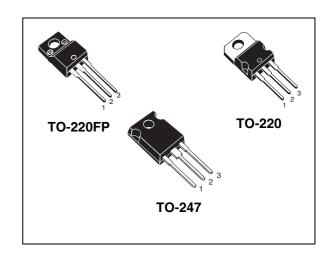


Figure 1. Internal schematic diagram

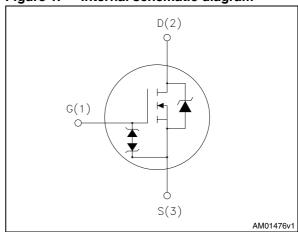


Table 1. Device summary

Order codes	Marking	Package	Packaging
STP12NK60Z	P12NK60Z	TO-220	Tube
STF12NK60Z	F12NK60Z	TO-220FP	Tube
STW12NK60Z	W12NK60Z	TO-247	Tube

October 2009 Doc ID 11324 Rev 7 1/15

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
	2.1 Electrical characteristics (curves)	6
3	Test circuits	9
4	Package mechanical data	0
5	Revision history 1	4

1 Electrical ratings

Table 2. Absolute maximum ratings

Cumbal	Parameter	Value	Unit	
Symbol	Farameter	TO-220, TO-247	TO-220FP	Ollit
V _{DS}	Drain-source voltage (V _{GS} = 0)	600		V
V _{GS}	Gate-source voltage	±30		V
I _D	Drain current (continuous) at T _C = 25 °C	10	10 ⁽¹⁾	Α
I _D	Drain current (continuous) at T _C = 100 °C	6.3	6.3 ⁽¹⁾	Α
I _{DM} ⁽²⁾	Drain current (pulsed)	40	40 ⁽¹⁾	Α
P _{TOT}	Total dissipation at T _C = 25 °C	150	35	W
	Derating factor	1.2	0.27	W/°C
V _{ESD(G-S)}	Gate source ESD (HBM-C=100 pF, R=1.5 kΩ)		2500	V
dv/dt (3)	Peak diode recovery voltage slope	4.5		V/ns
V _{ISO} Insulation withstand voltage (RMS) from all three leads to external heat sink (t =1 s;T _C = 25 °C)		2500		V
T _{stg}	Storage temperature -55 to 150		50	°C
T _j	Max operating junction temperature	150	°C	

^{1.} Limited only by maximum temperature allowed

Table 3. Thermal data

Symbol	Parameter		Value			
Symbol	raiametei	TO-220 TO-247 TO		TO-220FP	Unit	
R _{thj-case}	Thermal resistance junction-case max	0.83		3.6	°C/W	
R _{thj-amb}	Thermal resistance junction-ambient max 62.5 50		62.5	°C/W		
T _I	Maximum lead temperature for soldering purpose	300		°C		

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by Tj Max)	10	Α
E _{AS} Single pulse avalanche energy (starting Tj=25°C, I _D =I _{AS} , V _{DD} =50 V)		260	mJ

^{2.} Pulse width limited by safe operating area

^{3.} $I_{SD} \leq$ 10 A, di/dt \leq 200 A/ μ s, V_{DD} = 480 V

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 5. On/off

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	600			٧
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V_{DS} = Max rating V_{DS} = Max rating, T_{C} =125 °C			1 50	μA μA
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 20 V			±10	μA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 100 \mu A$	3	3.75	4.5	٧
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.53	0.64	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
g _{fs} ⁽¹⁾	Forward transconductance	V _{DS} =10 V _, I _D = 5 A	-	9	-	S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz,}$ $V_{GS} = 0$	-	1740 195 49	-	pF pF pF
Coss eq. (2)	Equivalent output capacitance	V _{GS} = 0, V _{DS} = 0 to 480 V	-	101	-	pF
t _{d(on)} t _r t _{d(off)} t _f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 300 V, I_{D} = 5 A, R_{G} =4.7 Ω V_{GS} = 10 V (see Figure 19)	-	22.5 18.5 55 31.5	-	ns ns ns ns
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 480 V, I_{D} = 10 A, V_{GS} = 10 V (see Figure 20)	-	59 10 32	-	nC nC nC

^{1.} Pulsed: pulse duration = 300 μs, duty cycle 1.5%

^{2.} $C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)		-		10 40	A A
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 10 A, V _{GS} = 0	-		1.6	V
t _{rr}	Reverse recovery time	$I_{SD} = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		358		ns
Q_{rr}	Reverse recovery charge	V _{DD} = 50 V	-	3		μC
I _{RRM}	Reverse recovery current	(see Figure 24)		17		Α
t _{rr}	Reverse recovery time	$I_{SD} = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		460		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 50 \text{ V}, T_j = 150 ^{\circ}\text{C}$	-	4.2		μC
I _{RRM}	Reverse recovery current	(see Figure 24)		18.2		Α

- 1. Pulse width limited by safe operating area
- 2. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5%

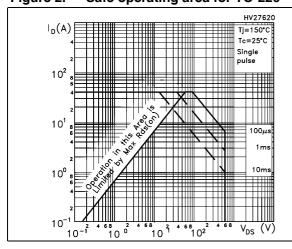
Table 8. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit	
BV _{GSO} (1)	Gate-Source breakdown voltage	Igs=± 1 mA (open drain)	30	-	-	٧	

The built-in back-to-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220 Figure 3. The



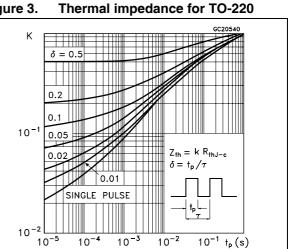


Figure 4. Safe operating area for TO-247

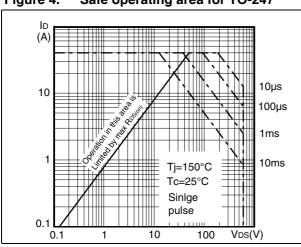


Figure 5. Thermal impedance for TO-247

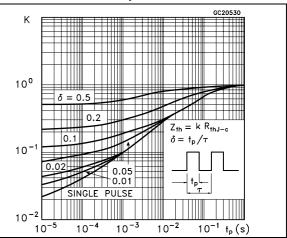


Figure 6. Safe operating area for TO-220FP

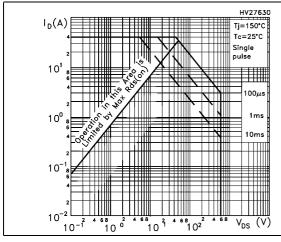


Figure 7. Thermal impedance for TO-220FP

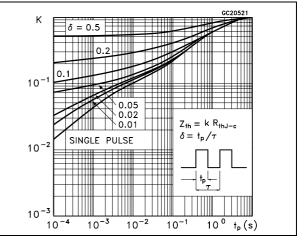


Figure 8. Output characteristics

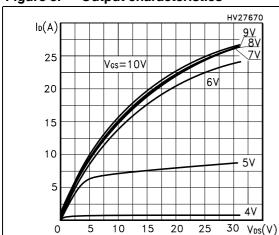


Figure 9. Transfer characteristics

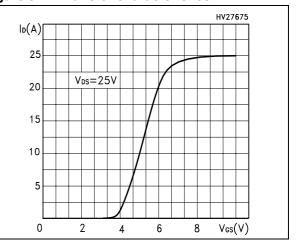


Figure 10. Transconductance

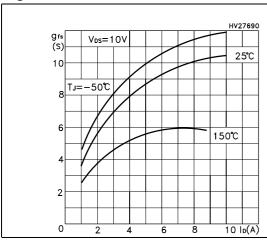


Figure 11. Static drain-source on resistance

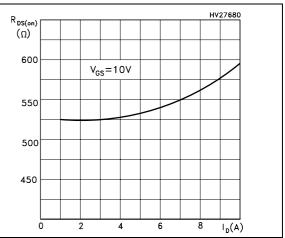
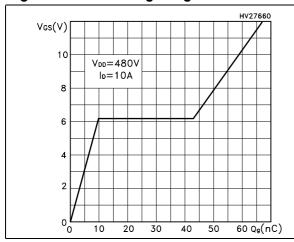


Figure 12. Gate charge vs gate-source voltage Figure 13. Capacitance variations



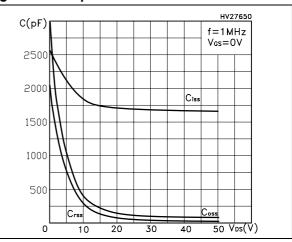
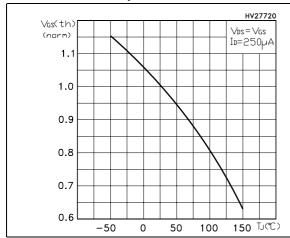


Figure 14. Normalized gate threshold voltage Figure 15. Normalized on resistance vs vs temperature temperature



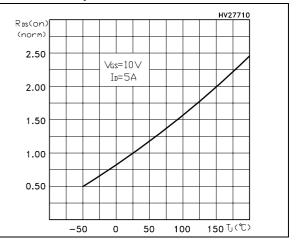
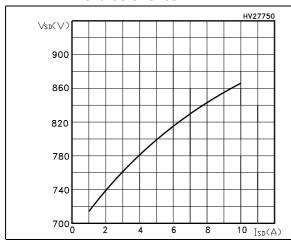


Figure 16. Source-drain diode forward characteristics

Figure 17. Normalized breakdown voltage vs temperature



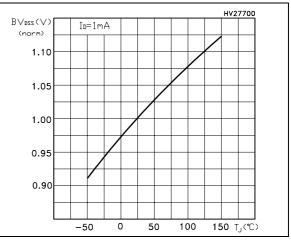
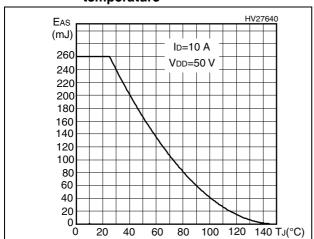


Figure 18. Maximum avalanche energy vs temperature



3 Test circuits

Figure 19. Switching times test circuit for resistive load

Figure 20. Gate charge test circuit

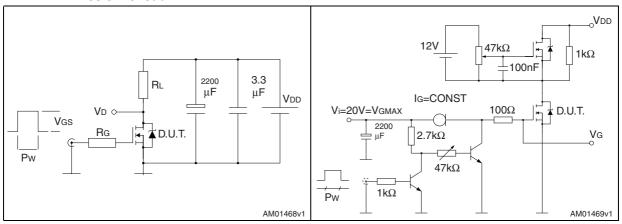


Figure 21. Test circuit for inductive load switching and diode recovery times

Figure 22. Unclamped inductive load test circuit

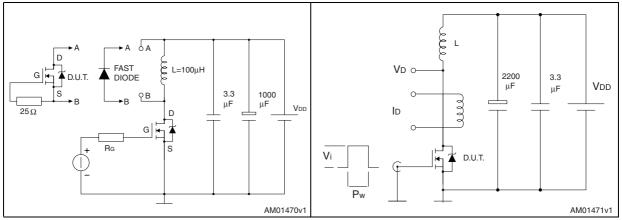
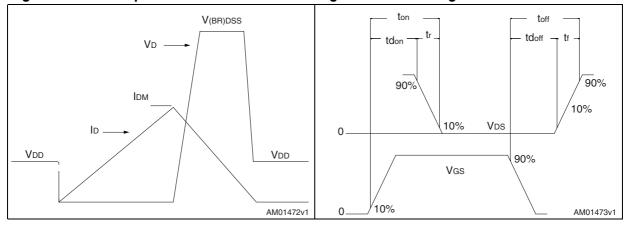


Figure 23. Unclamped inductive waveform

Figure 24. Switching time waveform

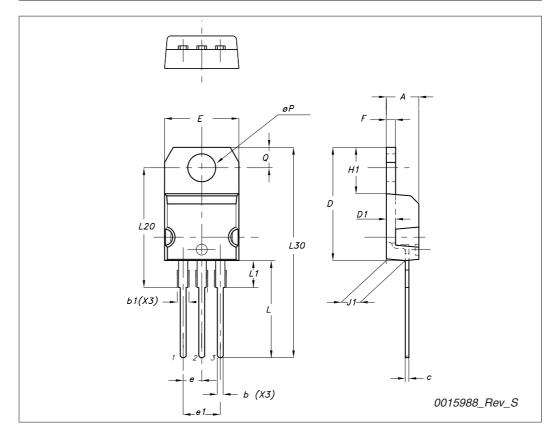


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

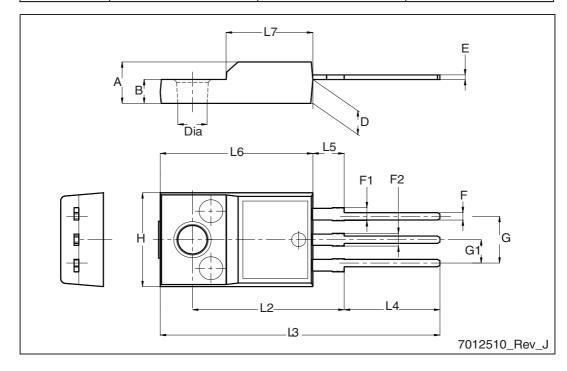
TO-220 type A mechanical data

D:			
Dim	Min	Тур	Max
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
С	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95



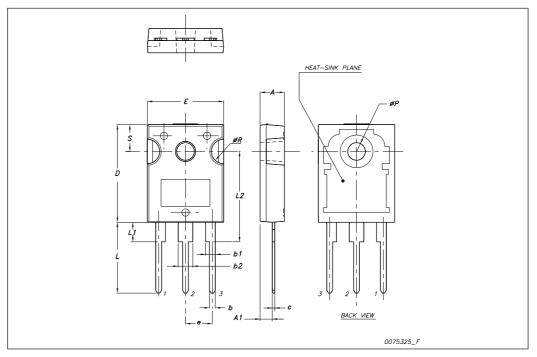
TO-220FP mechanical data

Dim.		mm	
Dilli.	Min.	Тур.	Max.
А	4.4		4.6
В	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.5
G	4.95		5.2
G1	2.4		2.7
Н	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2



TO-247 mechanical data

Dim.	mm.			
	Min.	Тур.	Max.	
A	4.85		5.15	
A1	2.20		2.60	
b	1.0		1.40	
b1	2.0		2.40	
b2	3.0		3.40	
С	0.40		0.80	
D	19.85		20.15	
E	15.45		15.75	
е		5.45		
L	14.20		14.80	
L1	3.70		4.30	
L2		18.50		
øΡ	3.55		3.65	
øR	4.50		5.50	
S		5.50		



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
12-Apr-2004	1	First release
06-Sep-2005	2	Inserted ecopack indication
13-Sep-2005	3	Final version
05-Sep-2006	4	The document has been reformatted
26-Apr-2007	5	The document has been updated on 1: Electrical ratings
25-Jan-2008	6	Modified: dv/dt value on Table 2: Absolute maximum ratings
13-Oct-2009	7	Added new package, mechanical data: TO-247

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